

*A 45th Symposium Update from
Chapter Vice-President, Dmitry Marchenko*



Dear Members, Friends and Colleagues!

On behalf of the iMAPS New England Chapter Executive Committee, I would like to thank all attendees for their outstanding support of our 44th Symposium in May of this year. We received some valuable feedback and will strive to make it even better in 2018.

Lee Levine from Process Solutions Consulting will be working together with his Session Chairs to bring an all-new exciting Technical Program to our May 1, 2018, 45th Annual Symposium and Expo on May 1, 2018.

We will be offering you the reports on the latest advancements in RF and Microwave Packaging, High Reliability Interconnects, MEMs, Photonics and Optoelectronics Packaging, Printed Electronics, and Medical Device Packaging. Make sure to check our website frequently and stay tuned for announcements of Technical Meetings and Symposium Technical Program updates.

We are always looking for energetic volunteers so, if you are interested in helping to organize the Symposium or Technical Meetings, please contact our President, Jon Medernach or me.

**I'm very pleased by your continued commitment,
Dmitry Marchenko, BAE Systems (dmitry.marchenko@live.com)
Vice-President iMAPS New England Chapter**